

**SO-CAU-OHB-RP-49****1. INSPECTED UNIT**

|               |           |
|---------------|-----------|
| Part number   | ---       |
| Part name:    | STEP-LVPS |
| Serial number | AA1       |
|               |           |

**2. INSPECTION TYPE**

|                                                    |                      |
|----------------------------------------------------|----------------------|
| Type of inspection<br>(solder, coating, final ...) | solder / gluing      |
|                                                    | Pass/ Fail/ Comments |
| Connectors/Saver                                   | Pass / NA            |
| Hardware assembly                                  | Pass                 |
| Gluing                                             | Pass                 |
| Soldering                                          | Pass                 |
| Cleanliness                                        | Pass                 |

**3. RESULTS**

|                  |                                                      |
|------------------|------------------------------------------------------|
| Part acceptable? | PCB accepted / zur weiteren Verarbeitung freigegeben |
|                  |                                                      |

**4. COMMENTS**Build due to Manufacturing Flow Chart: **STEP-LVPS-Board-OHB-XI-11**

On Digital-Board, all Flat-IC's have to be glued (gluing-plan prepared by CAU) on the LVPS-Board, the Flat-IC's (Flat10 and Flat14) don't have to be glued (gluing-plan prepared by OHB)

**5 SIGNATURE**Inspection performed: M. Quack  
Name29.03.2016  
Date

Signature







